Supplier Name:	**Texas Instruments Inc. (DUNS# 00-732-1904)**
Contact Info:	ti.com/support
Form/Declaration Type:	**Distribute - RoHS and IEC 62474 DB**
Created on:	**05/28/2022**

Details for "AM3354BZCED60"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package | Pins	Package body size (mm)	Total device mass (mg)*
AM3354BZCED60	SNAGCU	Level-3-260C-168 HR	TI PHILIPPINES A/T	ZCE | 298	13.0x13.0x0.89	397.6

***Total Device Mass**
The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

				Homogeneous Material Level		Component Level	
Component	**Substance**	**CAS Number**	**Amount (mg)**	**Percentage %**	**ppm**	**Percentage %**	**ppm**
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	1.539966	94.962557	949626	0.387302	3873
Not Categorized	Proprietary Materials		0.000252	0.01554	155	0.000063	1
Precious Metals	Gold	7440-57-5	0.017207	1.061076	10611	0.004328	43
Precious Metals	Palladium	7440-05-3	0.064231	3.960828	39608	0.016154	162
Sub-Total			**1.621656**	**100**	**1000000**	**0.407847**	**4078**
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	5.105424	81.999998	820000	1.284016	12840
Thermoplastics	Epoxy	85954-11-6	1.120703	18.000002	180000	0.281857	2819
Sub-Total			**6.226127**	**100**	**1000000**	**1.565873**	**15659**
Mold Compound							
Other Inorganic Materials	Aluminum Nitride	24304-00-5	2.173816	1	10000	0.546716	5467
Other Inorganic Materials	Fused Silica	60676-86-0	184.404793	84.83	848300	46.377872	463779
Other Nonferrous Metals and Alloys	Metal Oxide	Trade Secret	2.391197	1.1	11000	0.601387	6014
Other Organic Materials	Bromine	7726-95-6	0.043476	0.02	200	0.010934	109
Other Organic Materials	Chlorine	7782-50-5	0.043476	0.02	200	0.010934	109
Other Plastics and Rubber	Carbon Black	1333-86-4	0.652145	0.3	3000	0.164015	1640
Other Plastics and Rubber	Silicone	218163-11-2	1.739053	0.8	8000	0.437372	4374
Thermoplastics	Epoxy	85954-11-6	25.933622	11.93	119300	6.522315	65223
Sub-Total			**217.381578**	**100**	**1000000**	**54.671545**	**546715**
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	9.783571	100	1000000	2.460572	24606
Sub-Total			**9.783571**	**100**	**1000000**	**2.460572**	**24606**
Solder Ball							
Copper and Its Alloys	Copper	7440-50-8	0.367354	0.5	5000	0.09239	924
Nickel and Its Alloys	Nickel	7440-02-0	0.036735	0.049999	500	0.009239	92
Other Nonferrous Metals and Alloys	Tin	7440-31-5	72.185076	98.25	982500	18.154573	181546
Precious Metals	Silver	7440-22-4	0.88165	1.2	12000	0.221735	2217
Sub-Total			**73.470815**	**100**	**1000000**	**18.477936**	**184779**
Substrate							
Ceramics / Glass	Random E-Glass	65997-17-3	18.218618	20.4405	204405	4.581989	45820
Copper and Its Alloys	Copper	7440-50-8	36.259421	40.6815	406815	9.119257	91193
Nickel and Its Alloys	Nickel	7440-02-0	4.048641	4.5424	45424	1.018235	10182
Other Inorganic Materials	Inorganic Filler		10.484986	11.7637	117637	2.636978	26370
Other Nonferrous Metals and Alloys	Barium Sulfate	7727-43-7	2.833532	3.1791	31791	0.712634	7126
Other Plastics and Rubber	Other Filler		0.142608	0.16	1600	0.035866	359
Precious Metals	Gold	7440-57-5	0.658492	0.7388	7388	0.165611	1656
Thermoplastics	Epoxy	85954-11-6	16.483702	18.494	184940	4.145657	41457
Sub-Total			**89.13**	**100**	**1000000**	**22.416227**	**224162**
Total			397.613747			100	1000000

Important Note
The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.
See Glossary of Terms for more details.

Important Part Information
There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology
For an explanation of the methods used to determine material weights, See Product Content Methodology

Material Declaration Certificate for Semiconductor IC Packaged Products

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Signature: (click here for a fuller statement with a signed certificate)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality
For further environmental statements, please go to www.ti.com/ecoinfo
Created on: 05/28/2022

RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

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Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb203) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.